

ULTRAFAST RECOVERY RECTIFIER DIODE

1N5806D2A / 1N5806D2B

- Hermetic Ceramic Package Designed as a Drop-In Replacement for D-5A MELF Package
- Designed For High Rel Applications
- Screening Options Available



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise stated)

V_{RRM}	Maximum Reverse Repetitive Peak Voltage	150V
V_{RMS}	Maximum RMS Voltage	105V
V_{dc}	Maximum DC Blocking Voltage	150V
I_O	Maximum Rectified Current $I_{O2} = T_A + 55^\circ\text{C}^{(1)}$ Derate above $T_A 55^\circ\text{C}$	1.0A 8.33mA/°C
I_{FSM}	Non Repetitive Forward Surge Current $^{(2)}$	35A
T_J	Junction Temperature Range	-65 to +175°C
T_{stg}	Storage Temperature Range	-65 to +175°C

THERMAL PROPERTIES

Symbols	Parameters	Max.	Units
$R_{\theta JSP(IN)}$	Thermal Resistance, Junction To Solder Pads $T_{SP} = 25^\circ\text{C}$	34	°C/W
$R_{\theta JA(PCB)}$	Thermal Resistance, Junction To Ambient $^{(3)}$	150	°C/W

Notes

(1) I_{O2} is rated at 1.0A @ $T_A = 55^\circ\text{C}$ for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where $T_J(\text{Max})$ does not exceed 175°C; This equates to $R_{\theta JA(PCB)} \leq 154^\circ\text{C/W}$.

(2) $T_A = 25^\circ\text{C}$ @ $I_O = 1.0\text{A}$ and V_{RWM} for ten 8.3mS surges at 1 minute intervals.

(3) PCB = FR4, 0.0625 Inch (1.59mm) thick, single layer, 1.0-Oz Cu, Pad Size, (0.067" x 0.105") \ddagger , (1.7mm x 2.76mm) \ddagger , horizontal in still air.

\ddagger Recommended solder pad layout dimensions for this device, as detailed within this datasheet for the D-5A device.

Semelab Limited reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.



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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise stated)

Symbols	Parameters	Test Conditions	Min	Typ	Max	Units
V_F^*	Forward Voltage	$I_{FM} = 1.0\text{A}$			0.875	V
					$T_A = 125^\circ\text{C}$	
		$T_A = -65^\circ\text{C}$	1.075			
		$I_{FM} = 2.5\text{A}$	0.975			
I_R^*	Reverse Current	$V_R = 150\text{V}$			1.0	μA
					$T_A = 125^\circ\text{C}$	
V_{BR}^*	Breakdown Voltage	$I_{BR} = 100\mu\text{A}$		160		V
				$T_A = -65^\circ\text{C}$	150	

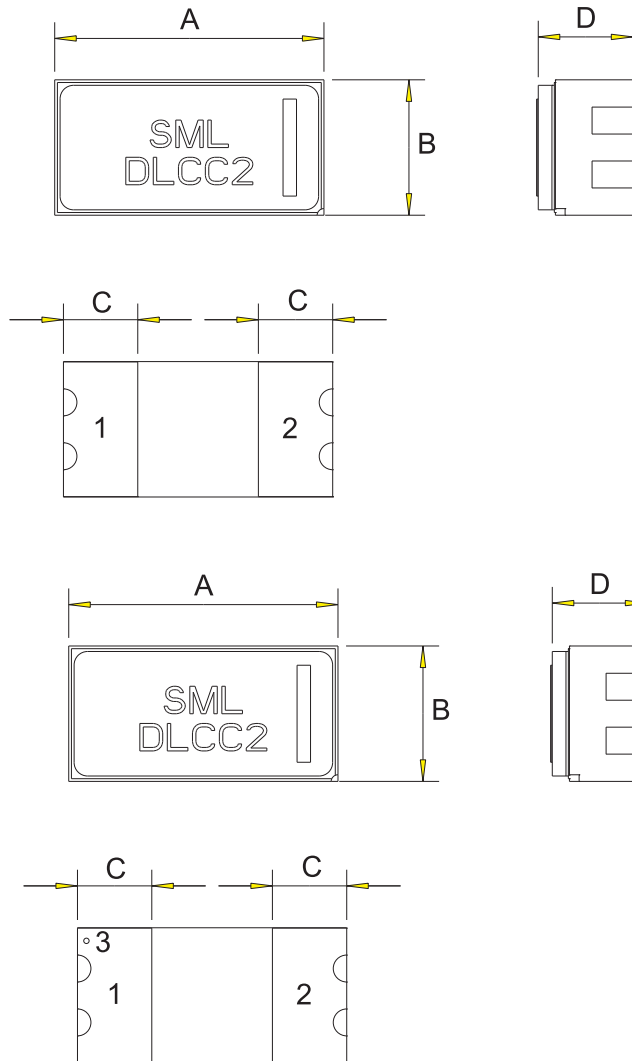
DYNAMIC CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise stated)

t_{rr}	Reverse Recovery Time	$I_F = I_{RM} = 0.5\text{A}$, $I_{(REC)} = 0.05\text{A}$ $di/dt = 65\text{A}/\mu\text{s}$		25		ns
C_J	Capacitance	$V_R = 10\text{V}$ $f = 1.0\text{MHz}$, $V_{sig} = 50\text{mV}$			25	pF

* Pulse Test: $t_p = 300\mu\text{s}$, Duty Cycle $\leq 2\%$

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MECHANICAL DATA



DLCC2 Variant A (D2A)

PAD 1	ANODE	
PAD 2	CATHODE	
DIMENSION	mm	Inches
A	5.00 ±0.10	0.197 ±0.004
B	2.61 ±0.10	0.103 ±0.004
C	1.08 ±0.10	0.043 ±0.004
D	1.76 ±0.10	0.069 ±0.004

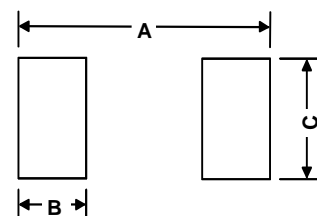
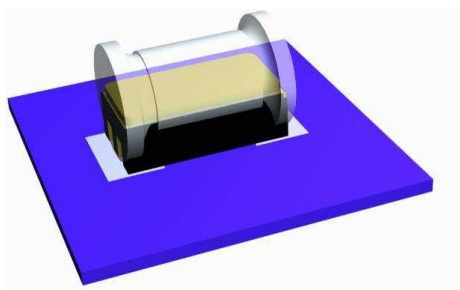
DLCC2 Variant B (D2B)

PAD 1	ANODE	
PAD 2	CATHODE	
PAD 3	LID CONTACT TO ANODE*	
DIMENSION	mm	Inches
A	5.00 ±0.10	0.197 ±0.004
B	2.61 ±0.10	0.103 ±0.004
C	1.08 ±0.10	0.043 ±0.004
D	1.76 ±0.10	0.069 ±0.004

SOLDER PAD LAYOUT D-5A

DIMENSION	mm	Inches
A	6.25	0.246
B	1.70	0.067
C	2.67	0.105

DLCC2/ D-5A MELF OVERLAY



* The additional contact provides a connection to the lid in the application. Connecting the metal lid to a known electrical potential stops deep dielectric discharge in space applications; see the Space Weather link www.semelab.co.uk/mil/lcc1_4 on the Semelab web site. Package variant to be specified at order.

Other Package Outlines may be available – Contact Semelab Sales to Enquire

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SCREENING OPTION

Space Level (JQRS/ESA) and High Reliability options are available in accordance with the [High Reliability and Screening Options Handbook](#) available for download from the from the TT electronics Semelab web site.

ESA Quality Level Products are based on the testing procedures specified in the generic ESCC 5000 and in the corresponding part detail specifications.

Semelabs QR216 and QR217 processing specifications (JQRS), in conjunction with the companies ISO 9001:2000 approval present a viable alternative to the American MIL-PRF-19500 space level processing.

QR217 (Space Level Quality Conformance) is based on the quality conformance inspection requirements of MIL-PRF-19500 groups A (table V), B (table VIa), C (table VII) and also ESA / ESCC 5000 (chart F4) lot validation tests.

QR216 (Space Level Screening) is based on the screening requirements of MIL-PRF-19500 (table IV) and also ESA /ESCC 5000 (chart F3).

JQRS parts are processed to the device data sheet and screened to QR216 with conformance testing to Q217 groups A and B in accordance with MIL-STD-750 methods and procedures.

Additional conformance options are available, for example Pre-Cap Visual Inspection, Buy-Off Visit or Data Packs. These are chargeable and must be specified at the order stage (See Ordering Information). Minimum order quantities may apply.

Alternative or additional customer specific conformance or screening requirements would be considered. Contact Semelab sales with enquires.

MARKING DETAILS

Parts can be laser marked with approximately 7 characters on two lines and always includes cathode identification. Typical marking would include part or specification number, week of seal or serial number subject to available space and legibility.

Customer specific marking requirements can be arranged at the time of order.

Example Marking:



ORDERING INFORMATION

Part numbers are built up from Type, Package Variant, and screening level. The part numbers are extended to include the additional options as shown below.

Type – See Electrical Stability Characteristics Table

Package Variant – See Mechanical Data

Screening Level – See Screening Options (ESA / JQRS)

Additional Options:

Customer Pre-Cap Visual Inspection	.CVP
Customer Buy-Off visit	.CVB
Data Pack	.DA
Solderability Samples	.SS
Scanning Electron Microscopy	.SEM
Radiography (X-ray)	.XRAY
Total Dose Radiation Test	.RAD
MIL-PRF-19500 (QR217)	
Group B charge	.GRPB
Group B destructive mechanical samples	.GBDM (12 pieces)
Group C charge	.GRPC
Group C destructive electrical samples	.GCDE (12 pieces)
Group C destructive mechanical samples	.GCDM (6 pieces)
ESA/ESCC	
Lot Validation Testing (subgroup 1) charge	.LVT1
LVT1 destructive samples (environmental)	.L1DE (15 pieces)
LVT1 destructive samples (mechanical)	.L1DM (15 pieces)
Lot Validation Testing (subgroup 2) charge	.LVT2
LVT2 endurance samples (electrical)	.L2D (15 pieces)
Lot Validation Testing (subgroup 3) charge	.LVT3
LVT3 destructive samples (mechanical)	.L3D (5 pieces)

Additional Option Notes:

- 1) All 'Additional Options' are chargeable and must be specified at order stage.
- 2) When Group B,C or LVT is required, additional electrical and mechanical destructive samples must be ordered
- 3) All destructive samples are marked the same as other production parts unless otherwise requested.

Example ordering information:

The following example is for the 1N5806 part with package variant B, JQRS screening, additional Group C conformance testing and a Data pack.

Part Numbers:

- 1N5806D2B-JQRS (Include quantity for flight parts)
- 1N5806D2B-JQRS.GRPC (chargeable conformance option)
- 1N5806D2B-JQRS.GCDE (charge for destructive parts)
- 1N5806D2B-JQRS.GCDM (charge for destructive parts)
- 1N5806D2B-JQRS.DA (charge for Data pack)

Customers with any specific requirements (e.g. marking or screening) may be supplied with a similar alternative part number (there is maximum 20 character limit to part numbers). Contact Semelab sales with enquiries.

High Reliability and Screening Options Handbook link: http://www.semelab.co.uk/pdf/misc/documents/hirel_and_screening_options.pdf